2SA748

Silicon PNP Epitaxial Planar Type

Medium Power Amplifier Complementary Pair with 2SC1398

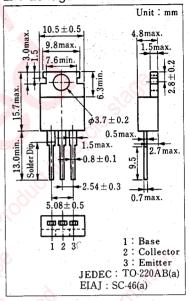
■ Features

- Large collector power dissipation (Pc)
- 10W output in complementary pair with 2SC1398

■ Absolute Maximum Ratings (Tc=25°C)

Item	Symbol	Value	Unit
Collector-base voltage	V _{CBO}	-70	V .
Collector-emitter voltage	V _{CEO}	-50	V
Emitter-base voltage	. V _{EBO}	-5	V
Peak collector current	I _{CP}	-3	Α
Collector current	Ic	-2	A
Collector power dissipation (Tc=25°C)	Pc	15	W
Junction temperature	Ti	150	c
Storage temperature	Tstg	$-55 \sim +150$	C

■ Package Dimensions

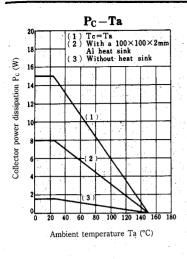


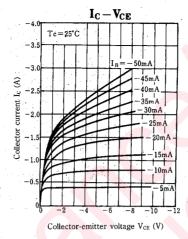
■ Electrical Characteristics (Tc=25°C)

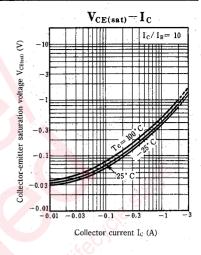
Item	Symbol	Condition	min.	typ.	max.	Unit	
	Ісво	$V_{CB} = -40V, I_E = 0$, C	-1	μΑ	
Collector cutoff current	I _{CEO}	$V_{CE} = -20 \text{ V}, I_{B} = 0$			-100		
Collector-base voltage	V _{CBO}	$I_C = -1 \text{ mA}, I_E = 0$	-70	9		V	
Collector-emitter voltage	V _{CEO}	$I_{c} = -10 \text{mA}, I_{B} = 0$	-50	·		V	
Emitter cutoff current	I _{EBO}	$V_{EB} = -5V, I_C = 0$.90		-100	μA	
DC current gain	h _{FE1}	$V_{CE} = -5 \text{ V}, I_C = -100 \text{ mA}$	30				
	h _{FE2} *	$V_{CE} = -5 \text{ V}, I_{C} = -1 \text{ A}$	30	130	220		
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -2A$, $I_B = -0.2A$		-0.6	-1.0	V	
Base-emitter saturation voltage	V _{BE(sat)}	$I_C = -2A$, $I_B = -0.2A$		-1.0	-1.5	V	
Transition frequency	f_{T}	$V_{CB} = -5V$, $I_E = 0.5A$, $f = 10MHz$		120		MHz	

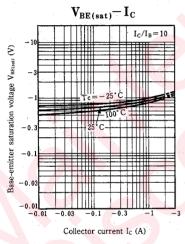
*h_{FE2} Classifications

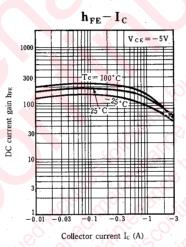
Class	P	Q	R
h _{FE2}	50~100	80~160	120~220

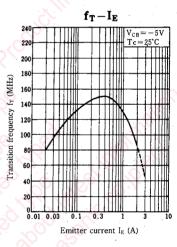


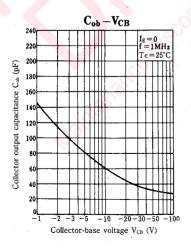


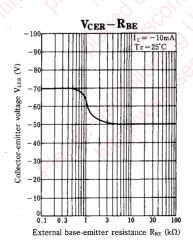


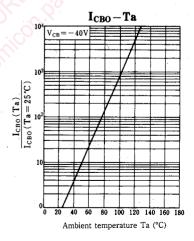


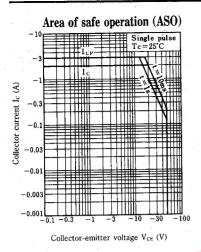


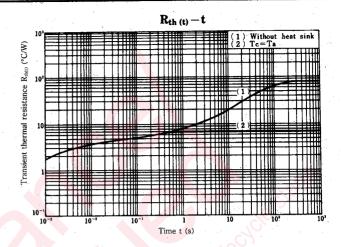












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